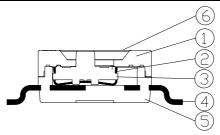
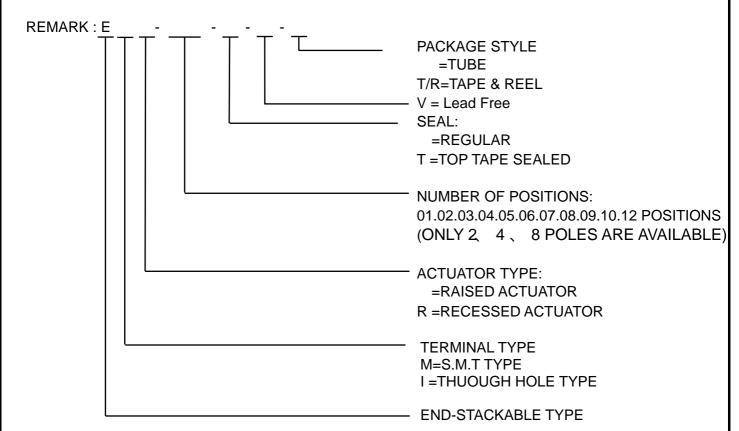


ITEM	DESC.	Q'TY	MATERIALS	TREATMENT	REMARK
1.	COVER	1	HIGH – TEMP. THERMOPLASTIC PA-9T UL 94V-0	MOLDED BLACK	-
2.	CONTACT	*	COPPER	GOLD PLATED AT CONTACT AREA.	-
3.	ACTUATOR	*	THERRMOPLASTIC LCP UL 94V-0	MOLDED WHITE	-
4.	TERMINAL	1	BRASS	GOLD PLATED	-
5.	BASE	1	HIGH – TEMP. THERMOPLASTIC PA9T UL 94V-0	MOLDED BLACK	-
6.	TAPE	1	KAPTON	-	-





Α	DWG.REL	
REV	ECO. NO	APPD

TITLE: END STACKABLE				APPD.	:	
TYPE DIP SWITCHES			CHKD.	:		
PRROD.	NO.:E	-	V-	PR.	: 7	楊佩儒
FILE	NO.: E-	V-C	D15	REV : A		SHEET: 1 of 1

EM(R), EI(R)- -V SPECIFICATION

文 件 編 號 : E-V-AD13 版 次 : A4 頁 次 : 1 / 4

1.Style:

This specification describes "DUAL IN-LINE PACKAGE SWITCHES" mainly used as signal switch of electric devices with the general requirements of mechanical and electrical characteristics.

1.1 Operating Temperature Range : -20 ~ +85 1.2 Storage Temperature Range : -40 ~ +85

2. Current Range:

2.1 Non-Switching: 100mA, 50V DC
2.2 Switching: 25mA, 24V DC
3. Type of Actuation: Actuated by sliding

4. Test Sequence :

	ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
ELECTRIC PERFORMANCE	1		By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product.
	2	1)To be measured between the two terminals associated with each switch pole. Resistance 2)Measurements shall be made with a 1kHz shall current contact resistance meter.		100mΩ max. (initial)
	3	Insulation Resistance	500V DC, 1 minute ± 5 sec.	100MΩ min.
	4	ing Voltage	500V AC (50Hz or 60 Hz) shall be applied between all the adjacent terminals and between the terminal and the frame for 1 minute.	There shall be no breakdown or flashover.
	5	Capacitance	1 MHz ± 10 kHz	5 pF max.
MECHANICAL PERFORMANCE	6	Operation Force	Applied in the direction of operation. ON→OFF OFF→ON IMPLIES TO SERVICE OF THE SERVICE OF TH	1000gf max (9.8N max)

EM(R), EI(R)- -V SPECIFICATION

文件編號: E-V-AD13 版次: A4 頁次: 2 / 4

	7	Stop Strength	A static load of 1 operating directio operated for a pe	n and pulling	There shall be no sign of damage mechanically.	
			1)Soldering Temperature :			
			PROD SERIES	TEMP	TIME	
		• • • •	THROUGH HOLE TYPE EI(R)	260 ±5	5±1 sec.	4)Ocatest Decistance
	8	Soldering Heat	SMT TYPE EM(R)			1)Contact Resistance : 200m Max
MECHANICAL PERFORMANCE		Resistance	2)Duration of Sol 5±1 sec. 3)Frequency of S 2 times max. (PCB is 1.6mm	oldering Prod	cess:	2)As shown in item 3~6
	9	Vibration	Shall be vibrated in accordance with Method 201A of MIL-STD-202F 1)Frequency: 10-55-10 Hz 1 min/cycle. 2)Direction: 3 vertical directions including the direction of operation. 3)Test Time: 2 hours each direction.			As shown in item 2~6
	10	Shock	Shall be shocked in accordance with Method 213B condition A of MIL-STD-202F 1)Acceleration: 50G. 2)Action Time: 11 ± 1 m sec. 3)Testing Direction: 6 sides. 4)Test cycle: 3 times in each direction			As shown in item 2~6
	11	Solderability	©EI(R) Soldering Temperature:245±3 Lead-Free solder: M705E JIS Z 3282 Class A (Tin 96.5%, Silver 3%, Copper 0.5%) ©EM(R) SEE PAGE 4/4 ③Flux: 5-10 seconds. ④Duration of solder Immersion: 5±1 sec.			No anti-soldering and the coverage of dipping into solder must more than 75% was requested.

EM(R)、	EI(R)-	-V SPECIFICATION
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文件編號: E-V-AD13 版次: A4 頁次: 3 / 4

DURABILITY	12	Measurements shall be made following the test set forth below: 1)25 mA, 24V DC resistive load 2)Rate of Operation: 15~20 cycles/ minute 3)Cycle of Operation: 2000 cycles.		1)As show in item 3,4 2)Contact Resistance: 500mΩ max. (final-after test)
WEATHER-PROOF	13	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: -40 ±3 2)Time: 96 hours	As shown in item 2~6
	14	Resistance High Temperatur e	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 85 ±2 2)Time: 96 hours	1)As shown in item 3~6 2)Contact Resistance: 100mΩ max.
WE	15	Resistance Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 40 ±2 2)Relative Humidity:90~95% 3)Time: 96 hours	 1)As shown in item 4,6 2)Contact Resistance: 100mΩ max. 3)Insulation Resistance: 10MΩ min.

EM(R), EI(R)- -V SPECIFICATION

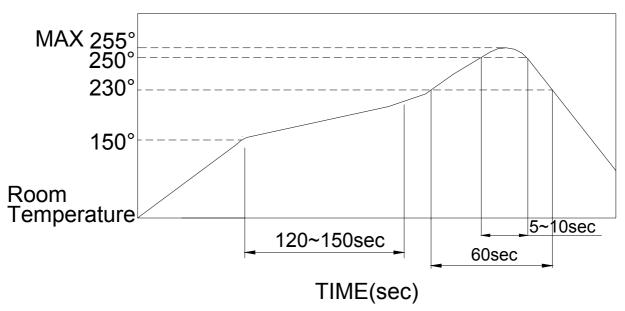
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5. SOLDERING CONDITIONS:

Condition for Soldering –EM(R) Series



■ The condition mentioned above is the temperature on the Cu foil of the P.C.B surface.

There are cases where board's temperature greatly differs from switch's surface temperature depending on board's material, size, thickness, etc. Care, therefore, should be used not to allow switch's surface temperature to exceed 255 .

■ Manual Soldering

Soldering Temperature	Max.350	
Continuous Soldering Time	Max. 5 seconds	

■ Precautions in Handling

- 1. Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch.
- 2. Don't clean the switch body except with top tape sealed type, which can only spray of cleaning method from top of s/w.
- 3. Please make sure that there is no flux rose over the surface of the PCB

